

AMENDMENT TO THE CLAIMS

Claims 1-27 (Cancelled)

28.(New) A packaged electronic device comprising:

- an electronic device;
- a first container member configured to mount said electronic device thereon;
- a second container member configured to form a space for housing said electronic device in corporation with said first container member;
- an adhesive configured to close the space by bonding said first container member and said second container member; and
- a metal film configured to cover an exposed face of said adhesive and an outer surface of said second container member.

29.(New) The packaged electronic device according to claim 28, wherein said first container member is a flat member and said second container member has a recessed part covering said first container member.

30.(New) The packaged electronic device according to claim 29, wherein said second container member has a flange part to be bonded to said first container member by said adhesive formed at the rim part of said recessed part.

31.(New) The packaged electronic device according to claim 28, wherein a moisture absorbent is installed in said space.

32.(New) A manufacturing method of a packaged electronic device comprising:

bonding a first container member on which an electronic device is mounted and a second container member configured to form a space for housing said electronic device in corporation with said first container member with an adhesive so as to close the space; and

covering an exposed face of said adhesive and an outer surface of said second container member with a metal film.

33.(New) A packaged electronic device comprising:

an electronic device;

a first container member configured to mount the electronic device thereon;

a second container member configured to form a space for housing said electronic device in corporation with said first container member; and

a metal layer configured to close said space by bonding said first container member and said second container member,

said metal layer being formed by radiating energy wave to surfaces of a first metal part of said first container member and a second metal part of said second container member while said first metal part and said second metal part are heated at a room temperature or higher and 150°C or lower in atmospheric air, and by bringing said first metal part and said second metal part into contact with each other.

34.(New) The packaged electronic device according to claim 33, wherein said metal layer is of gold.

35.(New) The packaged electronic device according to claim 33, wherein said first container member or said second container member is made of resin.

36.(New) A manufacturing method of a packaged electronic device comprising:

bonding a first container member on which an electronic device is mounted and a second container member configured to form a space for housing said electronic device in corporation with said first container member with a metal layer for closing the space;

when said bonding, radiating energy wave to a first metal part of said first container member and a second metal part of said second container member while said first metal part and said second metal part are heated at a room temperature or higher and 150°C or lower in atmospheric air; and

forming said metal layer by bringing said first metal part and said second metal part radiated with said energy wave into contact with each other.

37.(New) A packaged electronic device comprising:

a container configured to form a closed inner space by a first inner face, a second inner face on the opposite to said first inner face, and side faces perpendicular to said first inner face and said second inner face;

a first electronic device to be mounted on a first mounting face of said first inner face, second inner face, or side faces;

a second electronic device to be mounted on a second mounting face different from said first mounting face of said first inner face, second inner face, or side faces;

a first outer electrode formed on an outer face of said container facing to said first mounting face and configured to be electrically connected with said first electronic device; and

a second outer electrode formed on an outer face of said container facing to said second mounting face and configured to be electrically connected with said second electronic device,

said container including a recessed part; a main body member configured to mount said second electronic device on a bottom of said recessed part; a first cover member configured to be attached to an aperture of said recessed part and configured to mount said first electronic device; and a metal layer configured to close said inner space by bonding said main body member and first cover member,

said metal layer being formed by radiating energy wave to metal parts of said main body member and said first cover member while said metal parts are heated at a room temperature or higher and 150°C or lower in atmospheric air, and by bringing both radiated and heated metal parts into contact with each other.

38.(New) A manufacturing method of a packaged electronic device comprising:

 mounting a first electronic device to be connected electrically with a via on a first mounting face of a cover member having the via formed therein;

 mounting a second electronic device to be connected electrically with a via on a second mounting face of a main body member having the via formed therein and forming a closed inner space in corporation with said cover member; and

 forming a packaged electronic device by bonding said cover member and said main body member so as to arrange said first electronic device and said second electronic device in said inner space and thereby closing said inner space,

 said bonding of said cover member and main body member being carried out by:

 radiating energy wave to a first metal part formed on said first mounting face of said cover member and a second metal part formed on said main body member while said first metal part and said second metal part are heated at a room temperature or higher and 150°C or lower in atmospheric air; and

 thereafter, forming said packaged electronic device by bonding said cover member and main body member with said first metal part and said second metal part connected and closing said inner space.

39.(New) The manufacturing method of a packaged electronic device according to claim 38, wherein said electric connection of said vias with said first electronic device and second electronic device is carried out by radiating energy wave to said vias, and electrodes of said first electronic device and second electronic device; and thereafter bringing said vias into contact with said first electronic device and second electronic device.

40.(New) The manufacturing method of a packaged electronic device according to claim 38, wherein said electric connection of said vias with said first electronic device and second electronic device is carried out by providing a curable anisotropic conductive or non-conductive resin between electrodes of said first electronic device and second electronic device, and said vias.